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Serial No. 10/757,131

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PATENTS

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Application of:

DIANA, Daniel et al.

Serial No.: 10/747,824

Filed: December 29, 2003

Title: **METHOD AND APPARATUS FOR
FILLING INTERLAYER VIAS ON
FERROELECTRIC POLYMER
SUBSTRATES**

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Group Art Unit: 2823

Examiner: DANG, Trung Q.

Atty. Docket #: INTEL16

Assignee: Intel Corporation

O.K To ENTER

T. D

8/26/05

AMENDMENT AND RESPONSE TO FINAL OFFICE ACTION

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

This submission is in response to the Final Official Action mailed by the U.S. Patent and Trademark Office on June 16, 2005. As of this Official Action, pending claims 1 - 9, and 22 - 25 are allowed, claims 13 - 15 stand rejected, and claims 16, 17, and 19 - 21 are objected to. In response to this Final Official Action, it is respectfully requested that the Office consider the following remarks and amendments to the above-referenced application.